Advisory Board

Gary Lucas, Huddersfield University (UK)

Igor Emri, University of Ljubljana (Slovenia)

Masahisa Takashi, Professor Emeritus of Aoyama Gakuin University (Japan)

Michael Sutton, University of South Carolina (USA)

Olusegun J. Ilegbusi, University of Central Florida (USA)

Robert Mines, University of Liverpool (UK)

Tetsuo Mohri, Hokkaido University (Japan)

Yoshiharu Morimoto, Professor Emeritus of Wakayama University/Moire Institute Inc. (Japan)

Vasily Fomin, Institute of Theoretical and Applied Mechanics, Siberian Branch of Russian Academy of Sciences (Russia)

Local Executive Committee

Chairperson

Hiroshi Takahashi, Tohoku University (Japan)

Co-Chairpersons

Yuji Tanabe, Niigata University (Japan)

Hideaki Monji, University of Tsukuba (Japan)

Members

Ei Yamamoto, Kinki University (Japan)

Kenji Nakai, Okayama University of Science (Japan)

Mirei Chiba, Tohoku University (Japan)

Motoharu Fujigaki, Wakayama University (Japan)

Tomoaki Satomi, Tohoku University (Japan)

Noriaki Watanabe, Tohoku University (Japan)

Venue

The Symposium will take place at Sendai City War Reconstruction Memorial Hall, which is located in downtown of Sendai city. It takes about 20 minutes on foot from JR Sendai station to Sendai City War Reconstruction Memorial Hall.

ISEM Steering Board

Goichi Matsui, Professor Emeritus of University of Tsukuba (Japan) Manabu Iguchi, Hokkaido University (Japan)

Takashi Yokoyama, Okayama University of Science (Japan)

Registration

Registration by all participants, including invited speakers is mandatory. Please complete the registration form, following the instructions given below.

Registration Fee

Regular Fee: ¥40,000 (before September 20, 2013),

¥50,000 (after September 21, 2013)

Student Fee: ¥10,000 (before September 20, 2013), ¥15,000 (after September 21, 2013)

The regular fee covers Symposium attendance, a volume of program and abstracts, a piece of CD-ROM proceedings, reception, banquet, excursion and refreshments during coffee breaks. Note that the student fee does not cover either banquet or excursion.

Paper Submission, Selection, and Publication

Abstracts of 300-500 words in English should be submitted online at the Symposium website (template available):http://jsem.jp/ISEM8/submission.html. The abstracts should contain the following:

- (1) Title of paper.
- (2) Five keywords to describe and categorize the work.
- (3) Name, affiliation, address, e-mail address, telephone number and fax number of the author to whom subsequent correspondence should be directed.
- (4) Names and affiliations of co-authors, if any.
- (5) Background, objective, method, main findings and results.

The abstracts will be used for preliminary screening and planning for the sessions. Accepted abstracts should be submitted in the form of full-length manuscripts for review. Final acceptance will be based on review of the manuscripts. A bound volume of the abstracts and a piece of CD-ROM proceedings of the full-length papers will be available at the Symposium. Authors are invited to submit their papers for publication of a volume of selected papers or a Special Issue of Journal of the Japanese Society for Experimental Mechanics named as "Jikken Rikigaku". These submitted papers will be subject to the normal review process of the Journal.

Deadlines

Abstract submission: May 10, 2013

Notification of abstract acceptance: May 20, 2013 Full-length manuscript submission: July 10, 2013

Notification of full-length manuscript acceptance: August 30, 2013

Final manuscript due: September 24, 2013

For Further Information Contact

Professor Hiroshi TAKAHASHI

E-mail: isem2013@mail.kankyo.tohoku.ac.jp

Phone: +81-22-795-7394 Fax: +81-22-795-7394

Address: Graduate School of Environmental Studies

Tohoku University

6-6-20, Aoba, Aramaki, Aoba-ku, Sendai 980-8579, Japan

For further information please visit: http://jsem.jp/ISEM8/





Organized by:

The Japanese Society for Experimental Mechanics

Supporting Organizations:

The Society for Experimental Mechanics, Inc (USA)

The British Society for Strain Measurement (UK)

The Japan Society of Mechanical Engineers (Japan)

The Japanese Society for Multiphase Flow (Japan)

The Visualization Society of Japan (Japan)

Heat Transfer Society of Japan (Japan)

The Iron and Steel Institute of Japan (Japan)

The Japan Institute of Metals (Japan)

The Japanese Society for Non-destructive Inspection (Japan)

The Japan Society for Design Engineering (Japan)

The Japanese Society for Medical and Biological Engineering (Japan)

The Japanese Society for Clinical Biomechanics (Japan)

The Japanese Society for Terramechanics (Japan)

Scope and Topics



Background and Aims

The Japanese Society for Experimental Mechanics (JSEM) was founded in 2001 by reorganizing the former Japan Society for Photoelasticity to extend its covering area of Experimental Mechanics not only to Solid Mechanics but also to various areas of Applied Mechanics such as Fluid Mechanics, Thermal Engineering, Medical Engineering, Biomechanics, Construction and Civil Engineering and so on. The first Symposium was successfully held in Sapporo, Japan (2006) to attain its main purpose of the new establishment. The Symposium was subsequently held in Osaka, Japan (2007), Tainan, Taiwan (2008), Niigata, Japan (2009), Kyoto, Japan (2010), kansai, Japan (2011) and Taipei, Taiwan (2012).

The present Symposium aims to promote an exchange of recent and advanced information among scientists and engineers in the wide field of Experimental Mechanics with special focus on Environmental, Medical and welfare Engineering. The Symposium is also aimed particularly at promoting communication and collaboration between fundamental researchers and those engaged in the development of practical technology in respective areas of Experimental Mechanics. This Symposium title has been updated to The International Symposium on Advanced Science and Technology in Experimental Mechanics from the previous symposium. because the areas covered in the Symposium have been expanded as mentioned above.



Topics

We welcome papers in the following areas:

- (I) Fundamentals
 - (1) Fluid Dynamics
 - (2) Multiphase Flow
 - (3) Thermodynamics
 - (4) Heat and Mass Transfer
 - (5) Solid Mechanics / Strength of Materials
 - (6) Materials Science and Engineering
 - (7) Bioengineering
 - (8) Civil Engineering
 - (9) Sound and Vibration
 - (10) Instrumentation and Testing
 - (11) Visualization and Image Processing, and others
 - (12) Scale Modeling
- (II) Applications
 - (1) Fluid Machinery
 - (2) Fluid Flow in Micro- and Nano-scales
 - (3) Environmental Science and Engineering
 - (4) Advanced Energy and Power Systems
 - (5) Combustion Technology
 - (6) Medical and Welfare Engineering
 - (7) Biomechanics and Biomaterials
 - (8) Materials Processing
 - (9) Materials Testing and Fracture Mechanics Evaluation
 - (10) Non-destructive Testing and Inspection
 - (11) Optical Methods, Thermal Methods and X-ray Techniques
 - (12) Transducer and Sensor Design
 - (13) Safety Engineering, Risk Analysis and Reliability Methods
 - (14) Smart Materials and Structural Health Monitoring
 - (15) MEMS and NEMS
 - (16) Recycling
 - (17) Electronic Packaging, and others

Committees



Organizing Committee

Chairperson

Hiroshi Takahashi, Tohoku University (Japan)

Members

Charles W. Knisely, Bucknell University (USA)

Chyan-Bin Hwu, National Cheng Kung University (Taiwan)

Chien-Chi Ma, National Taiwan University (Taiwan)

Eisaku Umezaki, Nippon Institute of Technology (Japan)

Goichi Matsui, Professor Emeritus of University of Tsukuba (Japan)

Hae-Man Choi, Korea Research Institute of Standards & Science (Korea)

Jiun-Jih Miau, National Cheng Kung University (Taiwan)

Kazuo Arakawa, Kyushu University (Japan)

Kazuyoshi Nishihara, Osaka Electro-Communication University (Japan)

Koji Mori, Osaka Electro-Communication University (Japan)

Makoto Sakamoto, Niigata University (Japan)

Manabu Iguchi, Hokkaido University (Japan)

Pär Jönsson, Royal Institute of Technology (Sweden)

Ruey-Jen Yang, National Cheng Kung University (Taiwan)

Sakamon Devahastin, King Mongkut's University of Technology

Thonburi (Thailand)

Satoru Okamoto, Shimane University (Japan)

Takashi Yokoyama, Okayama University of Science (Japan)

Tateo Usui, Fukui University of Technology (Japan)

Tomomasa Uemura, Kansai University (Japan)

Vadim Lebiga, Institute of Theoretical and Applied Mechanics,

Siberian Branch of Russian Academy of Sciences (Russia)

Wei-Chung Wang, National Tsing Hua University (Taiwan)

Woei-Shyan Lee, National Cheng Kung University (Taiwan)

Yasushi Sasaki, POSTEC (Korea)

Yong-Tian Chew, National University of Singapore (Singapore)

Scientific Committee

Chairperson

Yuji Tanabe, Niigata University(Japan)

Co-Chairperson

Hideaki Monji, University of Tsukuba (Japan)

Members

Akira Kato, Chubu University (Japan)

Akira Hiratsuka, Osaka Sangyo University (Japan)

Fong-Chin Su, National Cheng Kung University (Taiwan)

Fumio Nogata, Gifu University (Japan)

Genta Kawahara, Osaka University (Japan)

Hideaki Endo, Tohoku University (Japan)

Hideki Ono, Osaka University (Japan)

Hideyuki Yasuda, Osaka University (Japan)

Kazuo Ohmi, Osaka Sangyo University (Japan)

Kazuyoshi Nakabe, Kyoto University (Japan)

Keh-Chin Chang, National Cheng Kung University, (Taiwan)

Kiyomi Mori, Takushoku University (Japan)

Koichi Kobayashi, Niigata University (Japan)

Masaru Ishizuka, Toyama Prefectural University (Japan)

Masayoshi Kikuchi, Tohoku University (Japan)

Mirei Chiba, Tohoku University (Japan)

Ningde Jin, Tianjin University (China)

Ryoji Tsujino, Setsunan University (Japan)

Satoshi Kakunai, University of Hyogo (Japan)

Satoru Yoneyama, Aoyama Gakuin University (Japan)

Seiji Miura, Hokkaido University (Japan)

Shigeo Fujikawa, Hokkaido University (Japan)

Shinzaburo Umeda, Fukuyama University (Japan)

Suh Ho Chung, Seoul National University (Korea)

Tadashi Narabayashi, Hokkaido University (Japan)

Tatsuya Ohmi, Hokkaido University (Japan)

Toshihiko Shakouchi, Mie University (Japan)

Toshio Ishii, JFE R&D (Japan)

Yei-Chin Chao, National Cheng Kung University (Taiwan)

Yoon Hyuk Kim, Kyung Hee University (Korea)



Technical Exhibition

The Symposium will make plans to exhibit current technologies for instrumentation, diagnosis and products developed by companies, corporations and universities.